## **ON Semiconductor®**



Title of Change:	Au to Cu wire conversion for Zener Diode assembled in TSOP6 and SC88 package in ON Semiconductor Seremban facility.		
Proposed Changed Material First Ship Date:	28 Dec 2021 or earlier if approved by customer		
Current Material Last Order Date:	04 Jun 2021 Orders received after the Current Material Last Order Date expiration are to be considered orders for new changed material as described in this PCN. Orders for current (unchang material after this date will be per mutual agreement and current material invent availability.		
Current Material Last Delivery Date: 27 Dec 2021 The Current Material Last Delivery Date may be subject to change based or of the current (unchanged) material inventory			
Product Category:	Active components – Discrete components		
Contact information:	Contact your local ON Semiconductor Sales Office or JianHao.See@onsemi.com		
PCN Samples Contact: Contact your local ON Semiconductor Sales Office to place sample order or <			
Sample Availability Date:	01 Jan 2021		
PPAP Availability Date:	01 Feb 2021		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or MohdAzizi.Azman@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.		
Change Category			
Category	Type of Change		
Process - Assembly	Change of direct material supplier, Change of lead frame finishing material / area (internal), Change of wire bonding		

### **Description and Purpose:**

Upon the expiration of this PCN, these devices will be built with copper wire at the same site for TSOP6 and SC88 package design. For SC88 package, device will be build with SC88 Ag stripe leadframe. Other BOM remain unchanged.

Datasheet specifications and product electrical performance remain unchanged.

Reliability qualification and full electrical characterization over temperature has been completed.

The copper wire is with higher thermal conductivity and lower resistivity which benefits for customer application.

	Before Change Description	After Change Description
Bond Wire	TSOP 6 Package 1.3 mils Tanaka Gold Wire TSOP 6 Package 1.3 mils Heraeus Bare 0	
Bond wire	TSOP 6 Package 0.8 mils Tanaka Gold Wire	TSOP 6 Package 0.8 mils Tanaka Bare Cu Wire
	SC88 Package 0.8 mils Tanaka Gold Wire	SC88 Package 0.8 mils Tanaka Bare Cu Wire
Leadframe	Leadframe   SC88 Cu plated leadframe   SC88 Ag stripe leadframe	

There is no product marking change as a result of this change.

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	vation for Change:	Process/Materials Change			
Anticipated impact on fit, form, function, reliability, product safety or manufacturability: No anticipated impacts.					to testing
tes Affected:					
N Semicondu	ctor Sites		External Foundry/Subcon	Sites	
N Semiconduct	or Seremban, Malaysia		None		
Marking of Parts/ Traceability of Parts assembled with Cu Wire will have a Date Code of WW01,2022 or later					
nange: eliability Data	a Summary: IE : SZTVS4201MR6T1G	i (1.3mil wire)			
hange: eliability Data V DEVICE NAIV MS: S63633 ACKAGE: TSOF	IE : SZTVS4201MR6T1G P6 EPOXY	· · ·	Condition	Internal	Booulte
hange: eliability Dat: V DEVICE NAM MS: S63633 ACKAGE: TSOF Test	IE : SZTVS4201MR6T1G P6 EPOXY Specification	n	Condition	Interval	Results
nange: eliability Data V DEVICE NAM MS: S63633 ACKAGE: TSOF Test HTRB	IE : SZTVS4201MR6T1G P6 EPOXY Specification JESD22-A108	n Ta=150°C, 100%		1008 hrs	0/231
hange: eliability Dat: V DEVICE NAM MS: S63633 ACKAGE: TSOF Test	IE : SZTVS4201MR6T1G P6 EPOXY Specification	n Ta=150°C, 100%	max rated V		
eliability Data V DEVICE NAM MS: S63633 ACKAGE: TSOF Test HTRB HTSL	IE : SZTVS4201MR6T1G P6 EPOXY JESD22-A108 JESD22-A103 MIL-STD-750 (M1037)	n Ta=150°C, 100% Ta=150°C Ta=+25°C, delta On/off = 2 min	max rated V	1008 hrs 2016 hrs	0/231 0/231
eliability Data V DEVICE NAM MS: S63633 ACKAGE: TSOF Test HTRB HTRB HTSL	IE : SZTVS4201MR6T1G 26 EPOXY <u>Specification</u> JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101	n Ta=150°C, 100% Ta=150°C Ta=+25°C, delta On/off = 2 min Ta= -55°C to +19	5 max rated V Tj=100°C 50°C, mount on board	1008 hrs 2016 hrs 30000 cyc	0/231 0/231 0/231
eliability Data V DEVICE NAIW VIS: S63633 ACKAGE: TSOF Test HTRB HTRL IOL TC	IE : SZTVS4201MR6T1G 26 EPOXY Specification JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101 JESD22-A104	n Ta=150°C, 100% Ta=150°C Ta=+25°C, delta On/off = 2 min Ta= -55°C to +19 130°C, 85% RH,	5 max rated V Tj=100°C 50°C, mount on board	1008 hrs     2016 hrs     30000 cyc     1000 cyc	0/231 0/231 0/231 0/231
eliability Data V DEVICE NAIV VIS: S63633 ACKAGE: TSOF Test HTRB HTSL IOL IOL TC HAST	IE : SZTVS4201MR6T1G 26 EPOXY Specification JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101 JESD22-A104 JESD22-A104	n Ta=150°C, 100% Ta=150°C Ta=+25°C, delta On/off = 2 min Ta= -55°C to +19 130°C, 85% RH, 3 130°C, 85% RH,	5 max rated V Tj=100°C 50°C, mount on board 18.8psig, bias	1008 hrs     2016 hrs     30000 cyc     1000 cyc     192 hrs	0/231 0/231 0/231 0/231 0/231
eliability Data V DEVICE NAN MS: S63633 ACKAGE: TSOF Test HTRB HTSL IOL IOL TC HAST UHAST	IE : SZTVS4201MR6T1G 26 EPOXY Specification JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101 JESD22-A104 JESD22-A110 JESD22-A118	n Ta=150°C, 100% Ta=150°C 100% Ta=+25°C, delta On/off = 2 min Ta= -55°C to +19 130°C, 85% RH, 130°C, 85% RH,	5 max rated V Tj=100°C 50°C, mount on board 18.8psig, bias 18.8psig, unbiased	1008 hrs     2016 hrs     30000 cyc     1000 cyc     192 hrs	0/231 0/231 0/231 0/231 0/231 0/231

## RMS: \$63650

# PACKAGE: TSOP6 EPOXY

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	2016 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	30000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C, mount on board	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/924
RSH	JESD22- B106	Ta = 265C, 10 sec		0/231
SD	JSTD002	Ta = 245C, 5 sec		0/231



## QV DEVICE NAME : SZSMF12CT1G (0.8mil wire & SC88 Ag strip leadframe) RMS: S66441

PACKAGE: SC-88 6 EPOXY

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	2016 hrs	0/231
TC	JESD22-A104	Ta= -55°C to +150°C, mount on board	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/693
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90
SD	JSTD002	Ta = 245C, 5 sec		0/45

## NOTE: AEC-1pager is attached.

To view attachments:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file.

### **Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
SZTVS4201MR6T1G	SZTVS4201MR6T1G	SZTVS4201MR6T1G
SZNSP4201MR6T1G	SZNSP4201MR6T1G	SZTVS4201MR6T1G
SZSMF12CT1G	SZSMF12CT1G	SZSMF12CT1G
SZSMF05CT1G	SZSMF05CT1G	SZSMF12CT1G
SZSMF05CT2G	SZSMF05CT2G	SZSMF12CT1G
SZSMS24CT1G	SZSMS24CT1G	SZSMS24CT1G



# Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
SZTVS4201MR6T1G		SZTVS4201MR6T1G	SZTVS4201MR6T1G	
SZSMF12CT1G		SZSMF12CT1G	SZSMF12CT1G	